Please amend the paragraph beginning on page 4, line 24, as follows:

According to the present invention, the treatment of the sapphire substrate with nitric

acid solution after the H<sub>2</sub> cleaning is carried out under the conditions at a nitric acid (HNO<sub>3</sub>)

concentration of 6% to 63% 6-63 wt. % and a temperature of 40°C for 0 to 10 minutes (min).

In contrast, the conventional high-temperature nitriding (comparative example) is carried out

under the conditions at a temperature of 750°C to 1100°C and a partial pressure of NH<sub>3</sub> of

50% for 5 minutes (min).

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